

- A' 8. (Amended) A semiconductor package, comprising:
- a substrate mounted with at least one semiconductor chip thereon and electrically connected to the semiconductor chip; and
 - an encapsulant formed by a molding compound injected into a molding cavity of a mold for encapsulating the semiconductor chip mounted on the substrate, wherein the molding cavity is formed with a plurality of recess portions, which are dimensioned to be relatively smaller in height than the molding cavity, and the recess portions are each connected to an air vent formed in the mold for interconnecting the recess portions and outside of the mold, such that the encapsulant is formed with a plurality of outwardly-extending portions by the molding compound filled in the recess portions of the molding cavity.

REMARKS

Claims 8-12 are pending in the application. Claims 1-7 were withdrawn from consideration, and have been canceled without prejudice. Claim 8 has been amended by the present amendment.

Enclosed is a Letter to Official Draftsman accompanied by a new set of formal drawings incorporating the drawing correction filed on December 27, 2002, which was approved by the Examiner.

Applicants' claimed invention is directed to a semiconductor package in which a semiconductor chip is mounted on a substrate and encapsulated by an encapsulant. The encapsulant is fabricated by injecting a molding compound into a molding cavity of a mold, wherein the molding cavity is formed with a plurality of recess portions, each recess portion having a smaller height than the molding cavity and connected to an air vent of the mold. As a result, the encapsulant is formed with a plurality of outwardly-extending portions (see reference numeral 28 in FIGS. 3A and 3B; see also specification at page 6, last full paragraph) by the molding compound filled in the recess portions.